



Docket No. 210093US2S

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Shotaro UCHIDA

SERIAL NO: 09/891,316

GAU: 2811

FILED: June 27, 2001

EXAMINER: JUNGHWA M. IM

RCE FILED: July 30, 2003

FOR: SEMICONDUCTOR DEVICE MANUFACTURING METHOD AND SEMICONDUCTOR DEVICE  
MANUFACTURED THEREBY

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 97

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- ☒ The applicant(s) wish to make of record the references cited in the attached Korean Office Action listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☐ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- ☒ Each item of information contained in this information disclosure statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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Form PTO 1449  
(Modified)U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE

ATTY DOCKET NO.

210093US2S

SERIAL NO.

09/891,316

## LIST OF REFERENCES CITED BY APPLICANT

APPLICANT

Shotaro UCHIDA

FILING DATE

June 27, 2001

RCE Filed: July 30, 2003

GROUP

2811

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION	
					YES	NO
	AO	59-27559	02/14/1984	JAPAN		X
	AP					
	AQ					
	AR					
	AS					
	AT					
	AU					
	AV					

## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

	AW	
	AX	
	AY	
	AZ	

☐ Additional References sheet(s) attached

Examiner

Date Considered

\*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Mailed Date: September 19, 2003  
Filing Due Date: November 19, 2003

**NOTIFICATION FOR FILING OPINION**

Applicant: name: Kabushiki Kaisha Toshiba

Application No.: 10-2001-0049306

Title of Invention: SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

As the result of examination of the present application, the following reasons for rejection have been found and notified herein under Section 63 of the Patent Law. Any opinion about the rejection [Form 25-2 attached to the Regulations under the Patent Law] or any amendment [Form 5 attached to the Regulations under the Patent Law] must be filed by the above date. (The above date is extensible by one month for each request. No notification of allowing extension of time will be issued.)

**[Reason]**

The matter described in claims 2-6 of the present application is unpatentable under the provision of Section 29 (2) of the Patent Law because, in the technical field the invention belonged to before this application, a person skilled in the art can easily provide the invention using the following.

**[Remarks]**

The inventions of claims 2-6 are related to a semiconductor device mounted on a die pad of lead frame. The semiconductor is characterized in that it comprises a semiconductor chip having a main electrode and a sub electrode with an area smaller than the main electrode, and an inner lead frame connected between the main electrode and sub electrode of the semiconductor chip, and the connection pad of an outer lead corresponding to the lead frame, and having a disconnected tie bar between each inner lead. The above

technical structure is disclosed in Jpn. Pat. Appln. KOKAI Publication No. 59-27559 (published February 14, 1984, thereafter the cited invention). Therefore, a person skilled in the art can easily perform the invention of claims 2-6 based on the cited invention.

[Attachment]

Jpn. Pat. Appln. KOKAI Publication No. 59-27559